

Vishay Siliconix

N-Channel 40-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$r_{DS(on)}\left(\Omega\right)$	I _D (A) ^a	Q _g (Typ.)		
40	0.037 at V _{GS} = 10 V	8	5.3 nC		
	0.046 at $V_{GS} = 4.5 \text{ V}$	8	5.5 110		

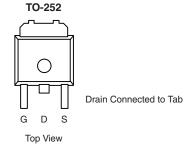
FEATURES

- TrenchFET® Power MOSFET
- 100 % UIS Tested

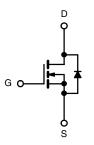


APPLICATIONS

- · Backlight Inverter for LCD Display
- Full Bridge DC/DC Converter



Ordering Information: SUD50N04-37P-E3 (Lead (Pb)-free)



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	$T_A = 25 ^{\circ}C$, unles	s otherwise no	oted		
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V_{DS}	40	V	
Gate-Source Voltage	V_{GS}	± 20			
	T _C = 25 °C		8 ^a		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		8 ^a		
Continuous Diain Current (1) = 150 C)	T _A = 25 °C	I _D	5.4 ^b		
	T _A = 70 °C		4.4 ^b	A	
Pulsed Drain Current		I _{DM}	30		
Continuous Source-Drain Diode Current	T _C = 25 °C	1	8 ^a		
Continuous Source-Drain Diode Current	T _A = 25 °C	l _S	1.6 ^b		
Single Pulse Avalanche Current L = 0.1 n		I _{AS}	7	1	
Avalanche Energy	L = 0.1 IIII1	E _{AS}	2.45	mJ	
	T _C = 25 °C	P _D	10.8	W	
Maximum Power Dissipation	T _C = 70 °C		6.9		
	T _A = 25 °C	' D	2.0 ^b		
	T _A = 70 °C		1.3 ^b	1	
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^b	Steady State	R_{thJA}	49	60	°C/W	
Maximum Junction-to-Case	Steady State	R _{thJC}	9.4	11.5		

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static						l	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	40			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			44		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \mu A$		- 5.5			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.4		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
7 0 1 1/1 5 1 0 1	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V			1	μΑ	
Zero Gate Voltage Drain Current		V _{DS} = 40 V, V _{GS} = 0 V, T _J = 70 °C			20		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	10			Α	
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = 10 V, I _D = 5 A		0.0305	0.037	Ω	
		V _{GS} = 4.5 V, I _D = 4 A		0.037	0.046		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 5 A		22		S	
Dynamic ^b							
Input Capacitance	C _{iss}			640		pF	
Output Capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		73			
Reverse Transfer Capacitance	C _{rss}			41			
Total Cata Chausa	0	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		11.7	20	nC	
Total Gate Charge	Q_g			5.3	9		
Gate-Source Charge	Q_{gs}	$V_{DS} = 20 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 5 \text{ A}$		1.9			
Gate-Drain Charge	Q_{gd}			1.7			
Gate Resistance	R_{g}	f = 1 MHz		2.2		Ω	
Turn-On Delay Time	t _{d(on)}			18	30	ns	
Rise Time	t _r	$V_{DD} = 20 \text{ V}, R_L = 4 \Omega$		14	25		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		14	25		
Fall Time	t _f			10	20		
Turn-On Delay Time	t _{d(on)}			9	18		
Rise Time	t _r	$V_{DD} = 20 \text{ V}, R_L = 4 \Omega$		11	20		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		14	25		
Fall Time	t _f			8	18		
Drain-Source Body Diode Characteris	tics						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			8	Α	
Pulse Diode Forward Current ^a	I _{SM}			1	30		
Body Diode Voltage	V_{SD}	I _S = 2 A		0.805	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			19	30	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 2 A, di/dt = 100 A/μs, T _J = 25 °C		14	25	nC	
Reverse Recovery Fall Time	ta			13		ns	
Reverse Recovery Rise Time	t _b			6		115	

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

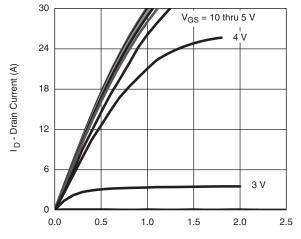
a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.



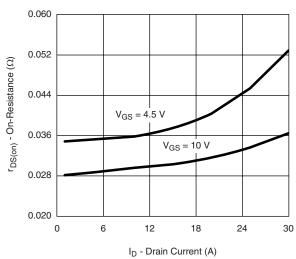
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

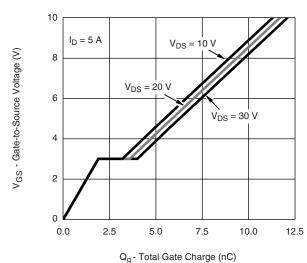


V_{DS} - Drain-to-Source Voltage (V)

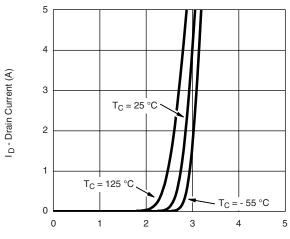




On-Resistance vs. Drain Current

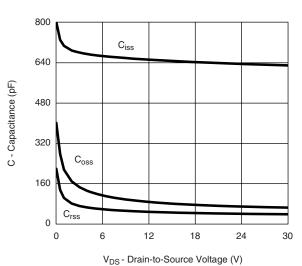


Gate Charge

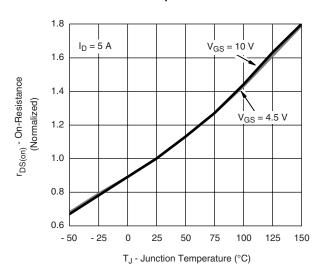


V_{GS} - Gate-to-Source Voltage (V)

Transfer Characteristics



Capacitance



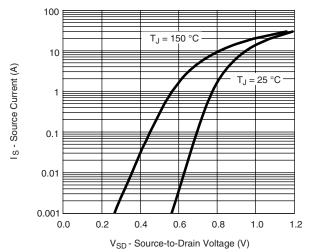
On-Resistance vs. Junction Temperature

SUD50N04-37P

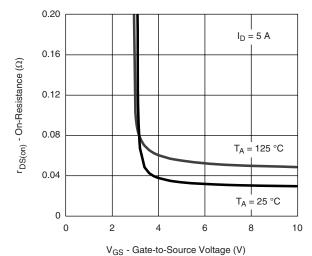
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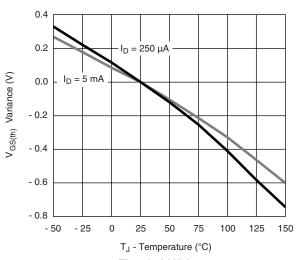
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



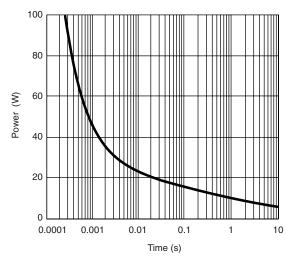
Source-Drain Diode Forward Voltage



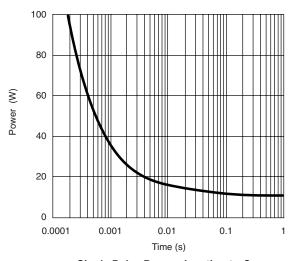
On-Resistance vs. Gate-to-Source Voltage



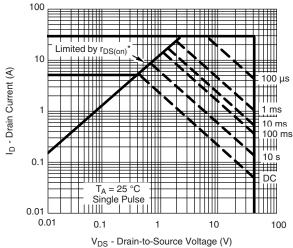
Threshold Voltage



Single Pulse Power, Junction-to-Ambient



Single Pulse Power, Junction-to-Case



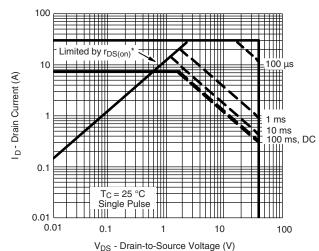
* V_{GS} > minimum V_{GS} at which r_{DS(on)} is specified

Safe Operating Area, Junction-to-Ambient



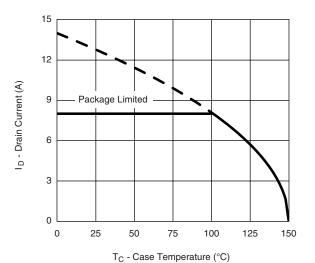
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

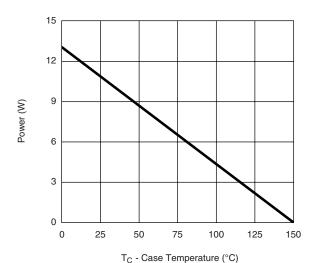


* V_{GS} > minimum V_{GS} at which r_{DS(on)} is specified

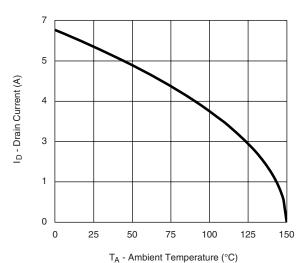
Safe Operating Area, Junction-to-Case



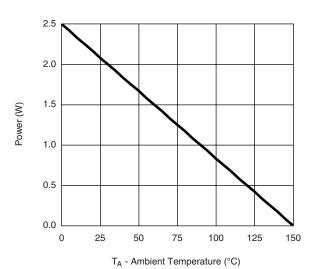
Current Derating*, Junction-to-Case



Power Derating*, Junction-to-Case



Current Derating*, Junction-to-Ambient



Power Derating*, Junction-to-Ambient

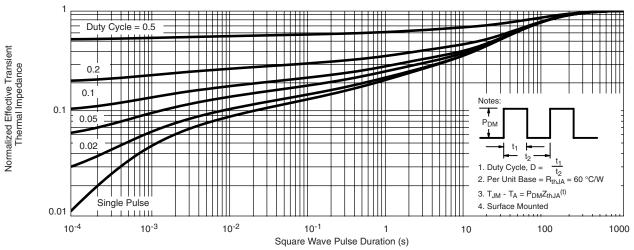
 $^{^{\}star}$ The power dissipation P_D is based on $T_{J(max)}=175\,^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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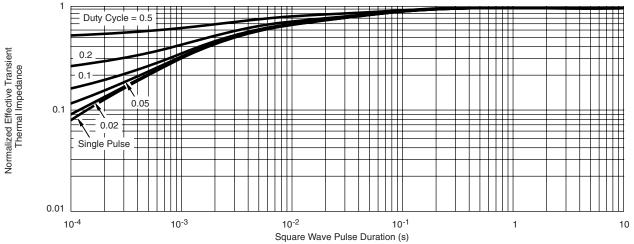
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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